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Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-09-21
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Antonella Lanzafame	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STP80NF06	TLDZ*ED5HA61	A	BOUSKOURA B/E	2015-09-21
Amount	UoM	Unit type	ST ECOPACK Grade	
1900.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10, 9.1, 4.5	3	THROUGH HOLE	
Comment	TO 220 AB NON ISOL			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TLDZ*EDSHA61					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	15.200	mg	supplier	die	Silicon (Si)	7440-21-3		14.693	mg	966645	7733
				supplier	metallization	Aluminium (Al)	7429-90-5		0.286	mg	18816	151
				supplier	Passivation	Silicon Oxide	7631-86-9		0.079	mg	5197	42
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.007	mg	461	4
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.100	mg	6579	53
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.035	mg	2303	18
Leadframe	Copper & its alloys	1259.453	mg	supplier	alloy	Copper (Cu)	7440-50-8		1251.376	mg	993587	658619
				supplier	alloy	Iron (Fe)	7439-89-6		1.253	mg	995	659
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.376	mg	299	198
				supplier	metallization	Nickel (Ni)	7440-02-0		6.408	mg	5088	3373
				supplier	metallization	Phosphorus (P)	12185-10-3		0.040	mg	32	21
				supplier	metallization	Phosphorus (P)	12185-10-3		0.040	mg	32	21
Soft solder	Solder	13.625	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	13.012	mg	955009	6848
				supplier	solder	Silver (Ag)	7440-22-4		0.341	mg	25028	179
				supplier	solder	Tin (Sn)	7440-31-5		0.272	mg	19963	143
				supplier	wire	Aluminium (Al)	7429-90-5		2.793	mg	999642	1470
				supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	358	1
				supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	358	1
Encapsulation	Other Organic Materials	602.566	mg	supplier	mold compound	Silica, vitreous	60676-86-0		524.232	mg	869999	275912
				supplier	mold compound	Epoxy resin	25068-38-6		60.257	mg	100001	31714
				supplier	mold compound	Phenol resin	29690-82-2		15.064	mg	25000	7928
				supplier	mold compound	Carbon Black	1333-86-4		3.013	mg	5000	1586
connections coating	Solder	6.362	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.362	mg	1000000	3348